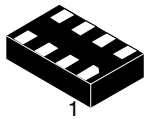


# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

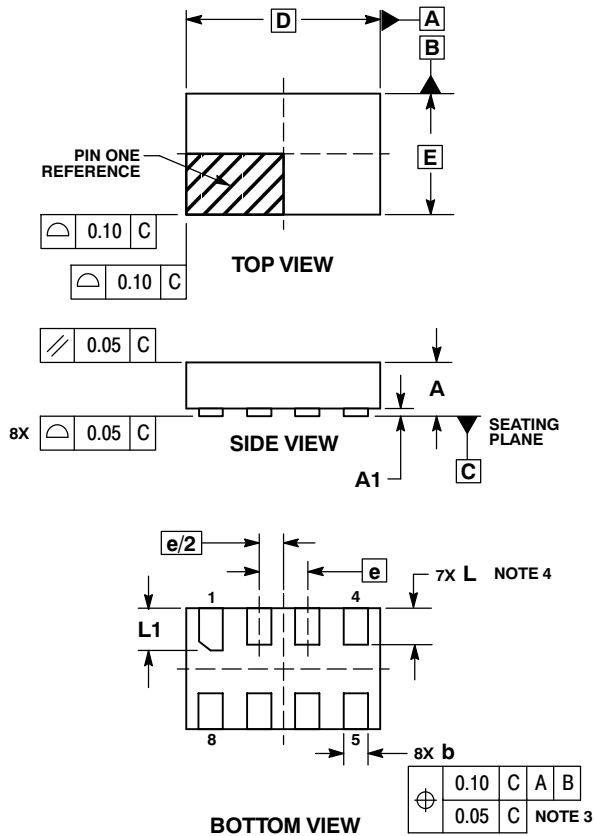
ON Semiconductor®



SCALE 8:1

ULLGA8, 1.6x1.0, 0.4P  
CASE 613AB-01  
ISSUE A

DATE 08 FEB 2008

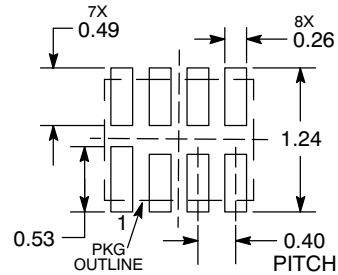


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

MILLIMETERS			
DIM	MIN	MAX	
A	---	0.40	
A1	0.00	0.05	
b	0.15	0.25	
D	1.60 BSC		
E	1.00 BSC		
e	0.40 BSC		
L	0.25	0.35	
L1	0.30	0.40	

**MOUNTING FOOTPRINT  
SOLDERMASK DEFINED\***



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>STATUS:</b>	ON SEMICONDUCTOR STANDARD	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	ULLGA8, 1.6X1.0, 0.4P	<b>PAGE 1 OF 2</b>

